



TECHNICAL REPORT



Device embedding assembly technology
Part 2-7: Guidelines – Accelerated stress testing of passive embedded circuit boards

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

DEVICE EMBEDDING ASSEMBLY TECHNOLOGY

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IEC TR 62878-2-7, which is a technical report, has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this technical report is based on the following documents:

| | |
|---------------|------------------|
| Enquiry draft | Report on voting |
| 91/1553/DTR | 91/1559/RVDTR |

Full information on the voting for the approval of this technical report can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62878 series, published under the general title *Device embedding assembly technology*, can be found on the IEC website.

Future standards in this series will carry the new general title as cited above. Titles of existing standards in this series will be updated at the time of the next edition.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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DEVICE EMBEDDING ASSEMBLY TECHNOLOGY

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1 Scope

This part of IEC 62878 describes the accelerated stress testing of passive embedded circuit boards. It can be used for screening finished boards, including multilayer and high-density interconnection (HDI) boards. These boards are mainly for mobile devices.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60194, *Printed board design, manufacture and assembly - Terms and definitions*